

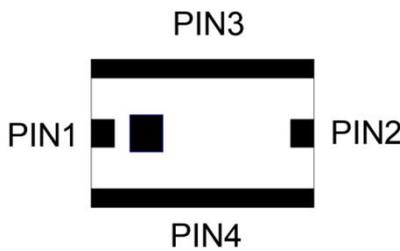
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

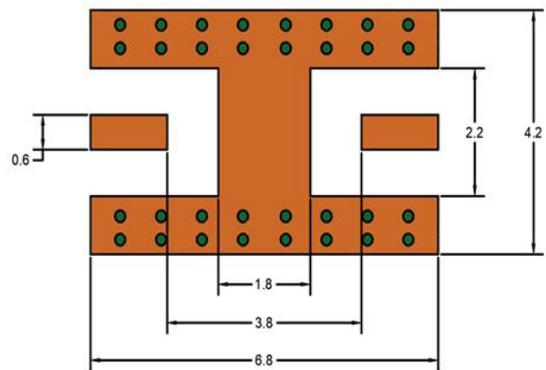
NO.	Parameter	SPEC
1	Frequency (MHz)	725~775
2	Insertion Loss (dB) @25°C	≤3.5
3	Ripple (dB)	≤1.0
4	VSWR(In BW)	≤1.8
5	Attenuation	1~450MHz
		1050~3500MHz
6	In/Output Impedance (Ω)	50
Operating & Storage Condition (Component)		
Operation Temperature Range: -40°C ~ +85°C		
Storage Temperature Range: -40°C ~ +85°C		
Storage Condition before Soldering (Included packaging material)		
Storage Temperature Range: +5 ~ +40 °C		
Humidity: 30 to 70% relative humidity		

Construction



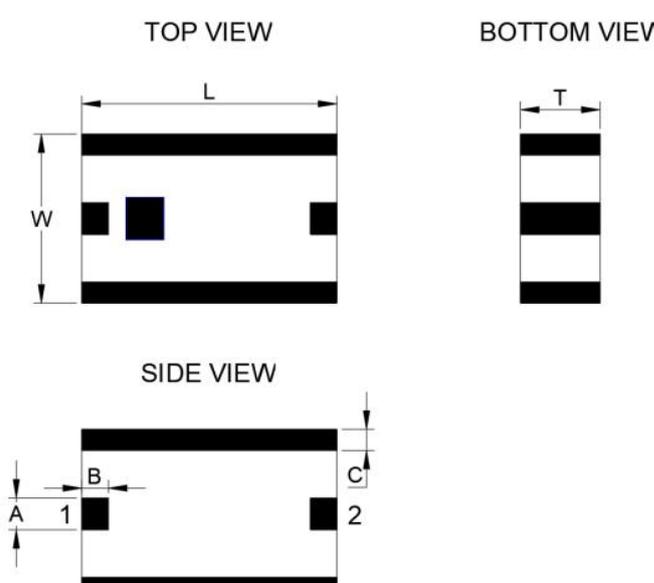
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

Mounting Considerations

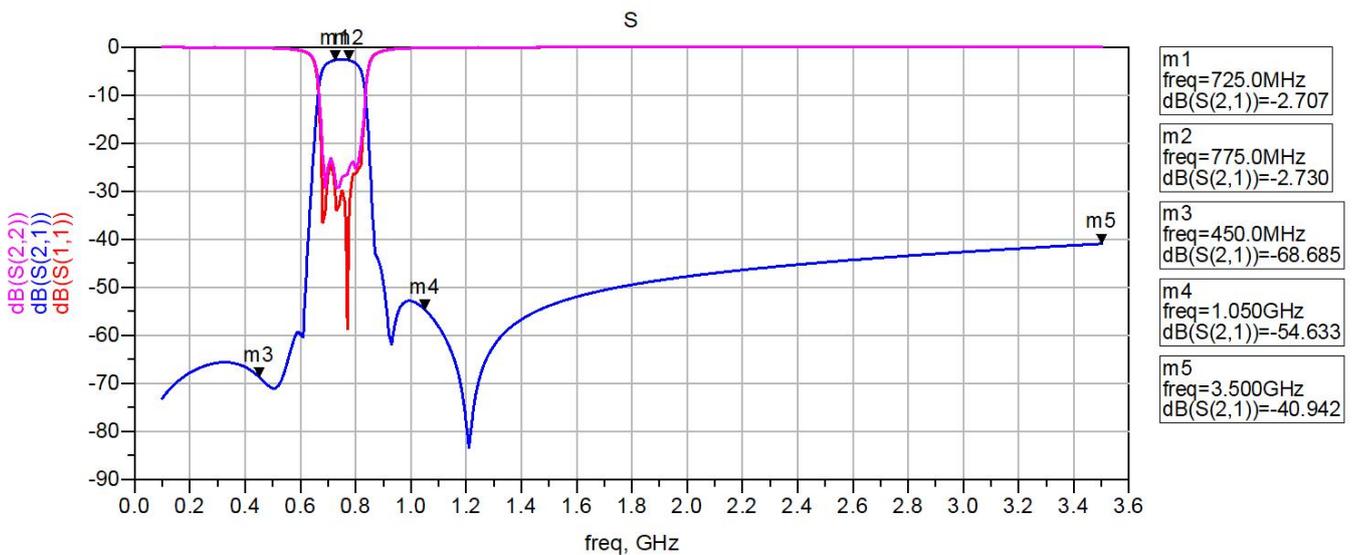


Unit: mm

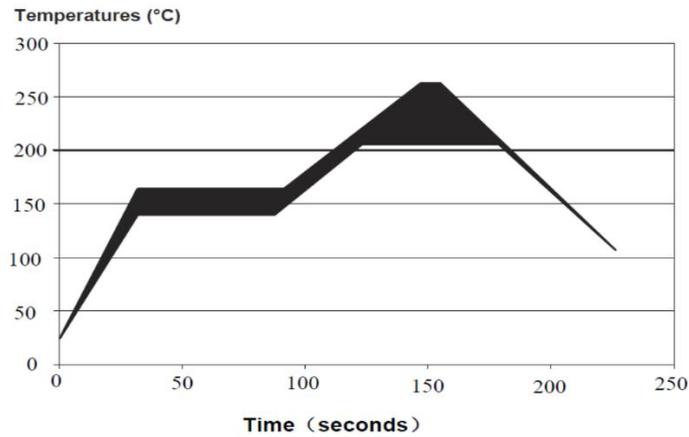
Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00 ± 0.20
	W	3.20 ± 0.20
	T	1.50 ± 0.20
	A	0.60 ± 0.10
	B	0.50 ± 0.10
	C	0.40 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.